



Initial Product/Process Change Notification

Document #: IPCN24110X

Issue Date: 22 Jun 2021

Title of Change:	Qualify Huatian Bump, Backgrind, Probe Test and DPS for increased manufacturing capacity for the FPF3188AUCX.
Proposed First Ship date:	30 Nov 2021 or earlier if approved by customer
Contact Information:	Contact your local ON Semiconductor Sales Office or Chung.Chang@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com> . Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>
Marking of Parts/ Traceability of Change:	Changed parts will be identified by the new plant code
Change Category:	Assembly Change
Change Sub-Category(s):	Manufacturing Site Addition

Sites Affected:**ON Semiconductor Sites**

None

External Foundry/Subcon Sites

Huatian Technology, China

Description and Purpose:

This initial Product Notification change is to qualify Huatian Bump, Backgrind, Probe Test and DPS for increased manufacturing capacity for the FPF3188AUCX.

There are no product material changes as a result of this change.

	Before Change Description	After Change Description
Bump Location Change	ASE KAOHSIUNG-TWN	Huatian Technology, China ASE KAOHSIUNG-TWN
Probe Location Change	ON Semiconductor Cebu	Huatian Technology, China ON Semiconductor Cebu
DPS Location Change	ON Semiconductor Cebu	Huatian Technology, China ON Semiconductor Cebu

The assembly site code will change on the product top mark as a result of this change.

	From	To
Product marking change	D=Cebu	D=Cebu, P2=Huatian

**Qualification Plan:**

QV DEVICE NAME: FPF3188AUCX

RMS: 57538

PACKAGE: WLCSP

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1000 hrs
HTSL	JESD22-A103	Ta= 150°C	1000 hrs
TC	JESD22-A104	Ta= -40°C to +125°C	850 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 3x reflow@ 260 °C	
SD	JSTD002	Ta = 245C, 5 sec	

Estimated date for qualification completion: 31 August 2021

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [**PCN Customized Portal**](#).

Part Number	Qualification Vehicle
FPF3188AUCX	FPF3188AUCX